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PREPARED BY: DATE:	CLIADO	SPEC. No. ED-90150B
N. Yasuda Jun 11.1996	SHARP	ISSUE June 10. 1996
	-	PAGE 12 Pages
APPROVED BY: DATE:	ELECTRONIC COMPONENTS GROUP SHARP CORPORATION	REPRESENTATIVE DIVISION
K. Making Jun 11, 1998	SPECIFICATION	OPTO-ELECTRONIC DEVICES DfV.
DEV	ICE SPECIFICATION FOR	<u> </u>
	PHOTOCOUPRER	
MOD	DEL No.	
	PC924 (Business dealing mms : PC024)	
((Business dealing mme : PC924))
	include materials protected under copyright of r cause anyone to reproduce them without Sha	
in these specification shee for any darnage resulting	please observe the absolute maximum ratings ets, as well as the precautions mentioned below from use of the product which does not comply ded in these specification sheets. and the prec	w. Sharp assumes no responsibility y with the absolute maximum ratings
(Precautions)		
	esigned for use in the following application are	
	nt • Audio visual equipment • Home appliar ication equipment (Terminal) • Measuring eq	
	hines • Computers	
	e product in the above application areas is for se be sure to observe the precautions given in th	
the safety design and safety when	sures, such as fad-safe design and redundant n of the overall system and equipment, should this product is used for equipment which dem n and precision, such as ;	be taken to ensure reliability
. Transportatio • Traffic signal (• Other safety	_	
(3) Please do not us	e this product for equipment which require ex action and precision, such as ;	tremely high reliability
	nent • Telecommunication equipment (for tru er control equipment • Medical equipment	ınk lines)
	nd consult with a Sharp sales representative if retation of the above three paragraphs.	there are any questions
3. Please contact and consult	with a Sharp sales representative for any que	estions about this product.
CUSTOMER'S APPRO	DATE VAL PRESENT BY	TED Matuina
DATE	Depa	latsumura, artment General Manager of ineering Dept. ,11
ВҮ	Opto	p-Electronic Devices Div. COM Group RP CORPORATION

1. Application

This specification applies to the outline and characteristics of OPIC photocoupler Model No. PC924.

2. Outline

Refer to the attached drawing No. CY4836K02.

3. Ratings and characteristics

Refer to the attached sheet, page 4 to 8.

4. Reliability

Refer to the attached sheet, page 9.

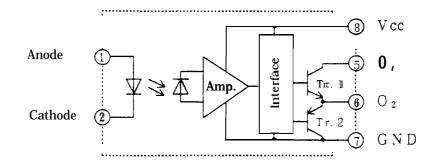
5. Incoming inspection

Refer to the attached sheet, page 10.

- 6. Supplement
 - 6.1 Isolation voltage shall be measured in the following method.
 - (1) Short among pins 1 to 4 on the primary side and among pins 5 to 8 on the secondary side.
 - (2) The dielectric withstand tester with zero-cross circuit shall be used.
 - (3) The wave form of applied voltage shall be a sine wave.(It is recommended that the isolation voltage be measured in insulation oil.
 - 6.2 The business dealing name used for this product when ordered or delivered shall be PC924.

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6.3 The block diagram, Table truth



Input	02 output	Tr. 1	Tr.2
ON	High level	ON	OFF
OFF	Low level	OFF	ON

6.4 This Model is approved by UL.

Approved Model No. : PC924

UL file No. : E64380

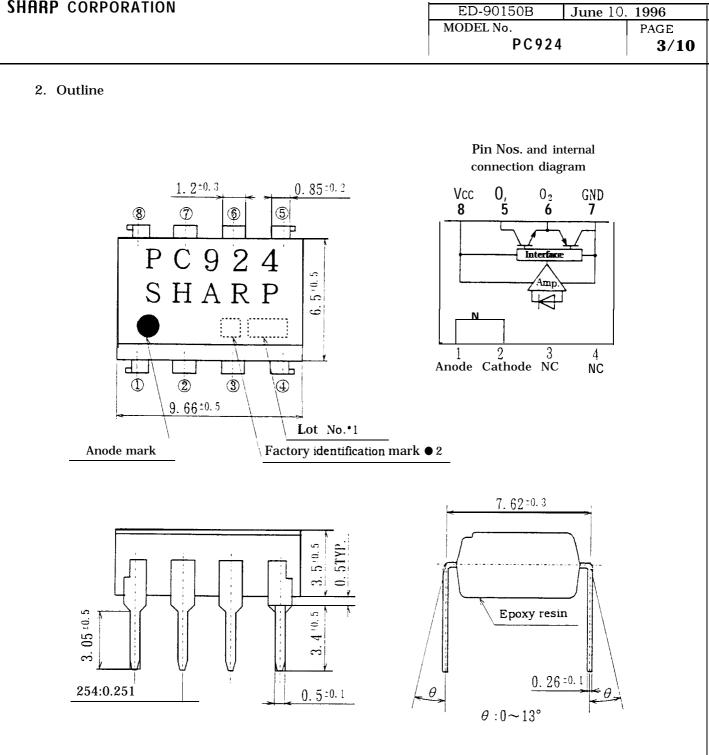
6.5 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

7. Notes

Refer to the attached sheet-1 -1.2.



- *1) 2-digit number shall be marked according to DIN standard.
- *2) Factory identification mark shall be or shall not be marked.

	UNIT: 1/1mm
Name	PC924 Outline Dimensions (Business dealing name : PC924)
Drawing No.	CY4836K02

3. Ratings and characteristics

3.1 Absolute maximum ratings

(Unspecified	:	Ta=Topr)
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	Parameter	Symbol	Rating	unit
Instruct	* 1 Forward current	IF	25	mA
Input	Reverse voltage	V _R	6(Ta=25 C)	v
	Supply voltage	Vcc	35	v
	O* Output current	10 ₁	0.1	Α
	*4 O, Peak output current	Io _{IP}	0.4	А
output	O ₂ Output current	10 ₂	0. 1	Α
	*4 O ₂ Peak output current	Io _{2P}	0.4	A
	O ₁ Output voltage	Vo ,	35	V
	*2 Power dissipation	Ро	500	mW
	*3 Total power dissipation	Ptot	550	mW
	*5 1s0 lation voltage	Viso	5.0	kVrms
	Operating temperature	Topr	-25 to +80	ʻc
	Storage temperature	Tstg	- 55 to +125	ʻc
	Soldering temperature	Tsol	260 (For 10 s)	Ĉ

*1, 2, 3 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig, 1, 2, 3.

*4 Pulse width $\leq 0.15 \,\mu$ s, Duty ratio :0.01

*5 AC for 1 rein, 40 to 60% RH , Ta=25 $^\circ\text{C}$

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3.2 Electro-optical characteristics

(Unspecified : Ta=Topr)

		1				-	(0)	
	Parameter	Symbol	MIN.	TYP	MAX	unit	l'est circuit	Conditions
	Forward voltage	V _{F1}	-	1.2	1.4	v		Ta=25°C, I _F =20mA
ut	C C	V _{F2}	0.6	0.9		V		Ta=25°C, I _F =0.2mA
Input	Reverse current	I _R	-	_	10	μA		Ta=25℃,V _R =4V
	Terminal capacitance	c t	/ -	30	250	pF		Ta.25'C , V=O, f=1kHz
	Operating supply voltage	Vcc	15		30	V		Ta=-10 to 60'C
	range	vee	15		24	V		
	O _I Low level output voltage	V _{OIL}	ŝ	0.2	0.4	v	(1)	Vcc ₁ =12V, Vcc ₂ =-12V I _{O1} =0.1A, I _F =10mA
	O_2 High level output voltage	V _{O2H}	18	21		v	(2)	Vcc=V ₀₁ =24V. I ₀₂ =-0.1A, I _F =10mA
put	O ₂ Low level output voltage	V _{022L}	-	1.2	2.0	V	(3)	VCC=24V, I _{O2} =0. 1A, I _F =0mA
Output	O ₁ Leak current	I _{o1L}	×		500	UA	(4)	Ta=25 'C, Vcc=V _{OI} =35V I _F =0mA
	O ₂ Leak current	I _{O2L}			500	μA	(5)	Ta.25°C , Vcc=V ₀₂ =35V I _F =10mA
	High level supply current	I _{CCH}	-	6	10	mA		Ta.25[°]C , VCC.24V I _F =10mA
			-		14	mA	(6	VCC=24V, $I_F = 10 \text{mA}$
	Low level supply current	I _{CCL}	-	8	13	mA	(0	Ta=25°C, Vcc=24V I _F =0mA
			-		17	mA		Vcc=24V, I _F =0mA

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3.2 Electro-optical characteristics

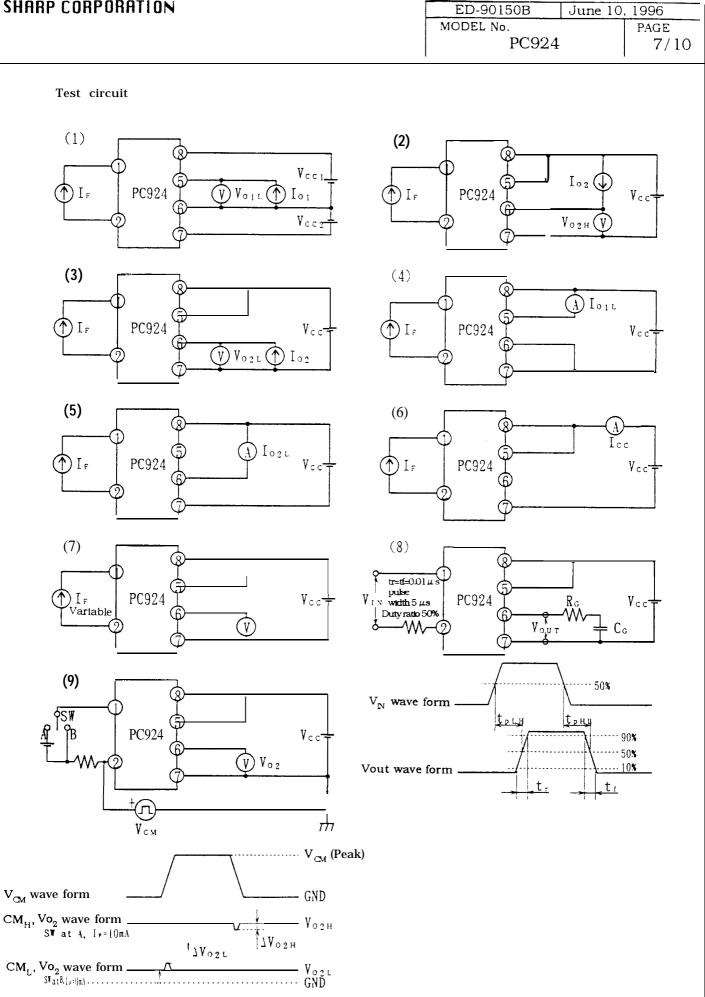
(Unspecified : Ta=Topr)

		Parameter	Symbol	MIN.	TYP.	MAX.	unit	'es t ircui	Conditions
		→H" threshold input Tent *2		1.0	4.0	7.0	mA	(7)	Ta=25°C,Vcc=24V
	Ju		ΊΗ	0.6	-	10.0	ШA	(7)	VCC=24V
ics	[so	lation resistance	Riso	5×10 ¹⁰	10''	-	Ω		Ta=25℃, DC500V 40 to 60%RH
Transfer characteristics	time	"L→H" propagation time	t _{PLH}		1.0	2.0			Ta=25 'C
harad		" $H \rightarrow L$ " propagation time	t _{PHL}		1.0	2.0		(8)	$Vcc=24V, I_F=10mA$
sfer c	sponse	Rise time	tr		0.2	0.5	μs	(0)	
Tran		Fall time	ťſ		0.2	0.5			$R_G = 47 \Omega \cdot C_G = 3000 pF$
	mo	tantaneous common de rejection voltage gh level output)	CM _H		-30000		·V/μs	(9)	Ta=25°C, Vcc=24V V _{CM} =600V(peak) $I_F=10mA, \Delta V_{O2H}=2.0V$
	mo	tantaneous common de rejection voltage w level output)	CML		30000	-	ν, μς	(8)	Ta=25°C, Vcc=24V V _{CM} =600V(peak) $I_F=0mA$, $\Delta V_{O2L}=2.0V$

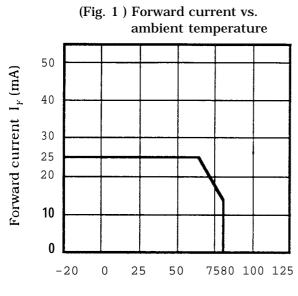
*1 It shall connect a by-pass capacitor of 0.01 μ F or more between Vcc (Pin No. 8) and GND (Pin No. 7) near the device, when it measures the transfer characteristics and the output side characteristics.

*2 I_{FLH} is the value of forward current when output becomes from " L" to "'H".

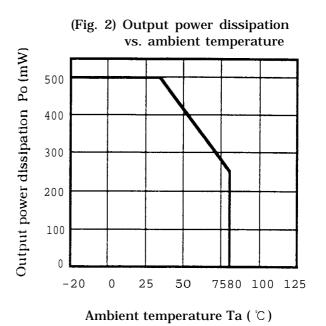
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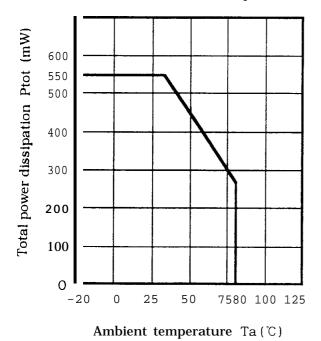
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Ambient temperature Ta ('C)



(Fig. 3) Total power dissipation vs. ambient temperature



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4. Reliability

The reliability of products shall be satisfied with items listed below.

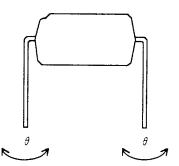
Confidence level : 90% LTPD : 10% / 20%

Test Items	Test Conditions *1	Failure Judgement Criteria	Samples (n) Defective(C)
Solderability *2	230°C, 5 s		n=11, C=0
Soldering heat	260°C.10 s	$V_F > U \times 1.2$	n=11, C=0
Terminal strength (Tension)	Weight : 5N 5 s /each terminal	$I_R > U \times 2$	n=11, C=0
Terminal strength (Bending) *3	Weight : 2.5N 2 times/each terminal	$v_{O1L} > U \times 1.2$ $v_{O2H} < L \times 0.8$	n=11, C=0
Mechanical shock	$15000 \text{ m/s}^2, 0.5 \text{ ms}$ 3 times/ ±X, ±Y, ±Z direction	v _{02L} >U×1.2	n=11, C=0
Variable frequency vibration	100 to 2000 to $100 \text{ Hz}/4\text{min}$ 200m/s ² 4 times/ X, Y, Z direction	$I_{O1L} > U \times 1.2$ $I_{O2L} > U \times 1.2$	n=11, C=0
Temperature cycling	1 cycle -55-C to +125°C (30min) (30min) 20 cycles test	$I_{CCH} > U \times 1.2$ $I_{CCL} > U \times 1.2$	n=22,C=0
High temp. and high humidity storage	+60℃,90%RH,1000h	I _{FLH} >Ux 1.3	n=22,C=0
High temp. storage	+125 °C , lOOOh	U: Upper specification	n=22,C=0
Low temp. storage	-55-C,1000h	limit L : Lower	n=22,C=0
Operation life	I _F =20mA, VCC=24V Ta=25°C, 1000h	specification limit	n=22,C=0

*1 Test method, conforms to JIS C 7021.

*2 Solder shall adhere at the area of 95% or more of immersed portion of lead and pin hole or other holes shall not be concentrated on one portion.

*3 Terminal bending direction is shown below.



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5. Incoming inspection

- 5.1 Inspection items
- (1) Electrical characteristics

 $V_{F}, I_{R}, V_{O1L}, V_{O2H}, V_{O2L}, I_{O1L}, I_{O2L}, I_{CCH}, I_{CCL}, I_{FLH}, Riso, Viso$

[2) Appearance

5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL(%)
Major defect	Electrical characteristics Unreadable marking	0.1
Minor defect	Appearance defect except the above mentioned.	0.4

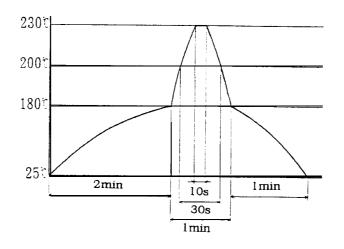
IP CORPORATION	ED-90150B	ED-90150B June 10. 1996		
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			sheet- 1-	
Precautions for Photocoupler	<u>s</u>			
1. For cleaning				
(1) Solvent cleaning : Solvent temperature 45° C or le	ess			
Immersion for 3 min or less				
(2) Ultrasonic cleaning : The affect to device by ultra		ferent		
by cleaning bath size, ultr				
output, cleaning time, PW condition etc. Please test i		•		
and confirm that doesn't o				
the ultrasonic cleaning.		0		
Applicable solvent : Ethyl alcohol. Methyl alcoho				
Freon TE · TF. Diflon-solven	t S3-E			
Please refrain form using ChloroFluoro Carbon	type solvent to clean			
device as much as possible since it is internatio	· ·			
the ozonosphere. Before you use alternative sol to confirm that it does not attack package resin.		ed		
to commin that it does not attack package resm.				
2. Please use the same as normal integration circuit a	bout static			
electricity in order that this device is OPIC photoco				
3. In order to stabilize power supply line, we should co	0			
a by-pass capacitor of 0.01 μ F or more between Vcc	and GND flear the d	evice.		
4. The LED used in the Photocoupler generally decreas	ses the light emission	1 power		
by operation. In case of long operation time, please			ing	
the decreases of the light emission newer of the LED	0		-	

the decreases of the light emission power of the LED. (50% / 5years) Please decide the input current which become 2 times of MAX. I _{FLH}.

SHARP CORPORATION ED-90150B June 10, 1996 MODEL No. PAGE PC924 Attach 5. Precautions for Soldering Photocouplers (1) In case of soldering An example of device temperature to lead vs. soldering time 180 260 °C 10 s or less 160 140 120 100 uuu Device 80 temperature 60 ('C) 40 20 Solder $^{\circ}$ 0 2 4 6 8 101214161820 Soldering time (s)

(2) If solder reflow :

It is recommended that only one soldering be done at the temperature and the time within the temperature profile as s hewn in the figure.



(3 Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item 2. Also avoid immersing the resin part in the solder.